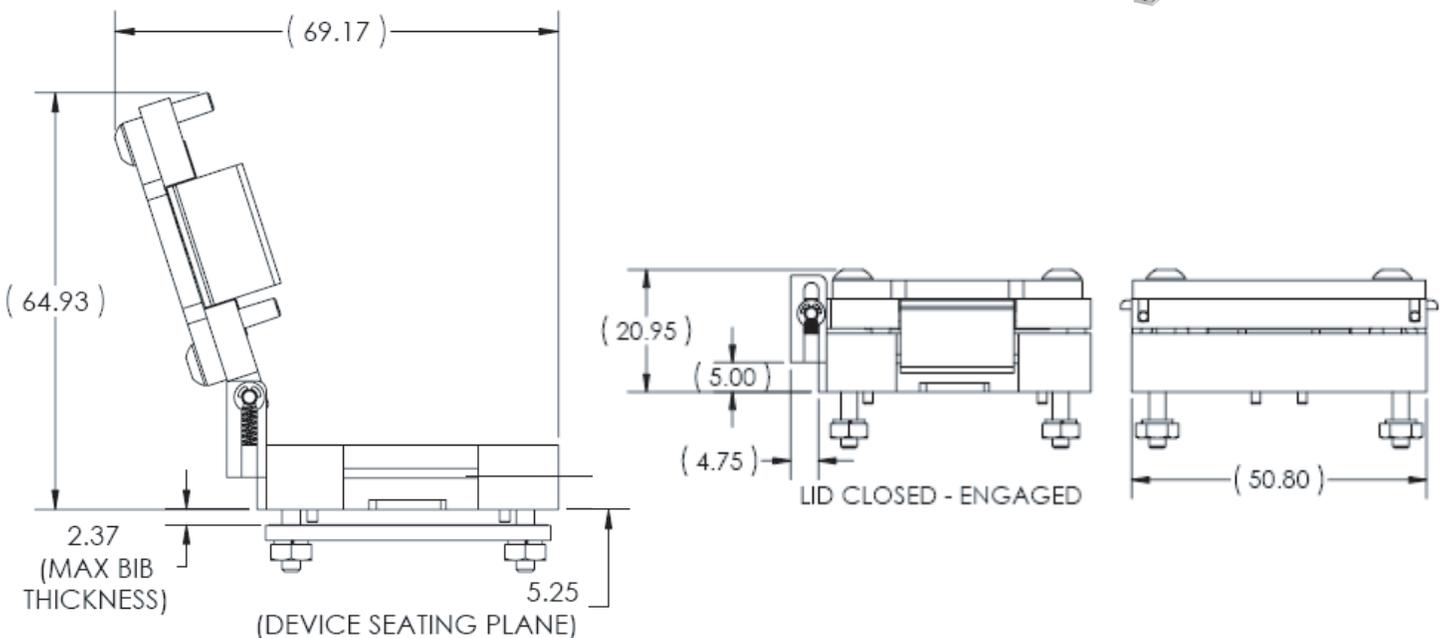




240 SERIES BGA/LGA

- Clamshell design, compression surface mount
- Spring and probe contact
- Max package size of 20 X 25mm
- Spring loaded pressure pad and locator plate
- Heat sinks available
- Any pitch or pitch combination .4mm and greater
- High performance contacts available



DESCRIPTION & ORDERING INFORMATION

240 - XXXX - XXX



MATERIALS & SPECIFICATIONS

- Contact Material: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Force: 12-15 grams typical
- Contact Resistance: 350 mΩ typical
- Temperature Rating: Burn-in 125°C
- Higher Temperatures consult factory